

5245 Hellyer Avenue San Jose, CA 95138 U.S.A. (408) 414-9200

Control No. PCN-23241 July 10, 2023

PRODUCT/PROCESS CHANGE NOTIFICATION

TY	PE OF CHANGE:	Design	Manufacturing	Other	
				f product/process change notifical Power Integrations sales office.	ation. If you
DES	CRIPTION OF CHANGE				
	Lapis Seminconductor alternative site for the	•		alified wafer fabrication site, will I	be added as an
REA	SON FOR CHANGE				
	Improvement in the m	nanufacturing capa	city and flexibility.		
PRC	DUCTS AFFECTED				
	Product Family		Ordering Part Number		Package
	LinkSwitch-CV	LNK623DG-TL			SO-8C
		LNK623PG			PDIP-8C
QU	ALIFICATION STATUS				
EFF	Refer to Appendix 1 fo	or the qualification	data.		
EFF	ECT ON CUSTOMER			no change to the datasheet para	imeters.
	ECT ON CUSTOMER			no change to the datasheet para	meters.
	ECT ON CUSTOMER No adverse impact is e	expected in manufa	acturers' applications. There is o change. Products fabricated	no change to the datasheet para at the current wafer fabrication s	
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Project Title: LNK623DG and LNK623PG Products Qualification at Lapis Miyagi Wafer Fab

Summary:

LNK623DG and LNK623PG products are being qualified at Lapis Miyagi to provide an alternative wafer fabrication site. Lapis Miyagi was previously qualified and has been in mass production of other products fabricated on the same wafer fabrication process since 2012. One lot of LNK623DG from Lapis Miyagi passed 1000 hours of DOPL testing for this qualification. Product electrical characterization was completed with acceptable results. Three additional lots of data on products using the same wafer fabrication process at Lapis Miyagi are included as supporting data.

Based on these results, Lapis Miyagi is qualified for wafer fabrication of LNK623DG and LNK623PG products.

Reliability Test Descriptions and Conditions

Test Name	Conditions	Reference Specification
DOPL (Dynamic Operating Life Test)	Tj=125°C, Vd _(peak) =580V	EIA/JESD22-A108-D
HTRB (High Temperature Reverse Bias Test)	Ta=150°C; Vd=580V, Vbp = 5.8V	EIA/JESD22-A108-D
THBT (Temperature Humidity Bias Test)	85°C, 85% RH, Vd=30V, Vbp = 5.8V	EIA/JESD22-A101-C
TMCL (Temperature Cycle, Air to Air)	-65°C to +150°C, air to air	EIA/JESD22-A104-E
HALT (Humidity Accelerated Life Test)	DOPL at Tj=115°C, 85% RH, Vd(peak)=580V	Internal Standard
	24-hr 150C bake → 168-hr 85°C, 85% RH	
MSL Preconditioning	soak for MSL1 or 192-hr 30°C, 60% RH soak	IPC/JEDEC J-STD-020E
	for MSL3 → 3 passes 260C solder reflow	

DOPL (Dynamic Operating Life)

Product	Lot #	Wafer Fab	Test Duration	No. Failures/Sample Size
LNK623DG	DT700A	Lapis Miyagi	MSL1 +1000 hours	0 / 45
TNY288DG	7B740G	Lapis Miyagi	MSL1 +1000 hours	0 / 45
TNY290PG	3E056B	Lapis Miyagi	1000 hours	0 / 45
TNY290PG	3E057A	Lapis Miyagi	1000 hours	0 / 45

HTRB (High Temperature Reverse Bias)

Product	Lot #	Wafer Fab	Test Duration	No. Failures/Sample Size
TNY288DG	7B740G	Lapis Miyagi	MSL1 +1000 hours	0 / 45
TNY290PG	3E057A	Lapis Miyagi	1000 hours	0 / 45
TNY290PG	3E057B	Lapis Miyagi	1000 hours	0 / 45

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THBT (Temperature Humidity Bias)

Product	Lot #	Wafer Fab	Test Duration	No. Failures/Sample Size
TNY288DG	7B740G	Lapis Miyagi	MSL1 +1000 hours	0 / 45
TNY290PG	3E056B	Lapis Miyagi	1000 hours	0 / 45
TNY290PG	3E057A	Lapis Miyagi	1000 hours	0 / 45

TMCL (Temperature Cycling)

Product	Lot #	Wafer Fab	Test Duration	No. Failures/Sample Size
TNY288DG	7B740G	Lapis Miyagi	MSL1 + 1000 cycles	0 / 45
TNY290PG	3E056B	Lapis Miyagi	1000 cycles	0 / 45
TNY290PG	3E057A	Lapis Miyagi	1000 cycles	0 / 45

HALT (Humidity Accelerated Life Test)

Product	Lot #	Wafer Fab	Test Duration	No. Failures/Sample Size
TNY288DG	7B740G	Lapis Miyagi	MSL1 +1000 hours	0/20
TNY290PG	3E056B	Lapis Miyagi	1000 hours	0 / 20
TNY290PG	3E057A	Lapis Miyagi	1000 hours	0 / 20

Conclusion: Based on acceptable results, LNK623DG and LNK623PG products are qualified for wafer fabrication at Lapis Miyagi.

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CUSTOMER ACKNOWLEDGEMENT

Power Integrations requests you acknowledge the receipt of the above-mentioned PCN. If no acknowledgment is received within 30 days of this notification, Power Integrations will assume the change is acceptable. Lack of any additional response within 90 days of this notification further constitutes acceptance of the change.

Power Integrations reserves the right to ship either version manufactured after the effective date.

The indicated Product/Process Change Notification was received by the undersigned authority.

If you have any questions or need further assistance, please contact your regional Power Integrations sales office. Otherwise, please check the box below, acknowledging the receipt of the PCN.

Email Address/Phone#:_______Company/Location:

CUSTOMER COMMENTS

Please email this signed form to pcn@power.com specifying the PCN# in the subject.

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